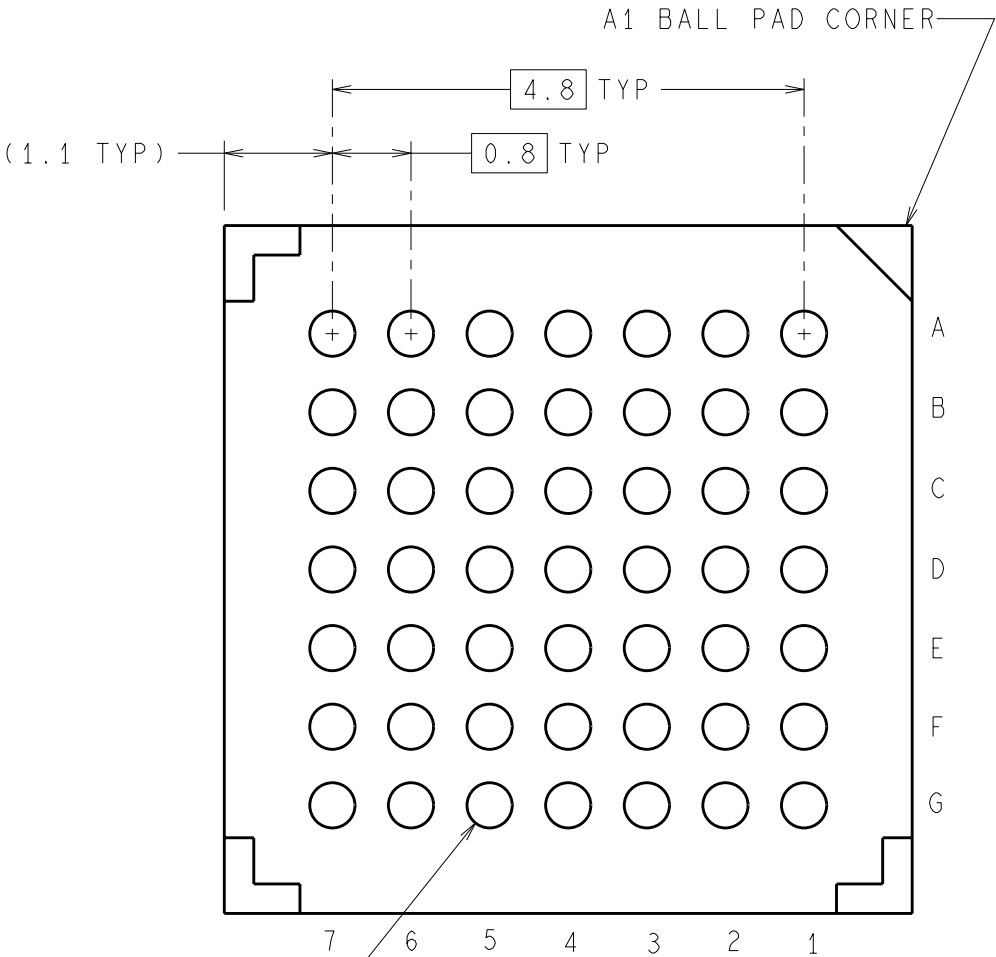
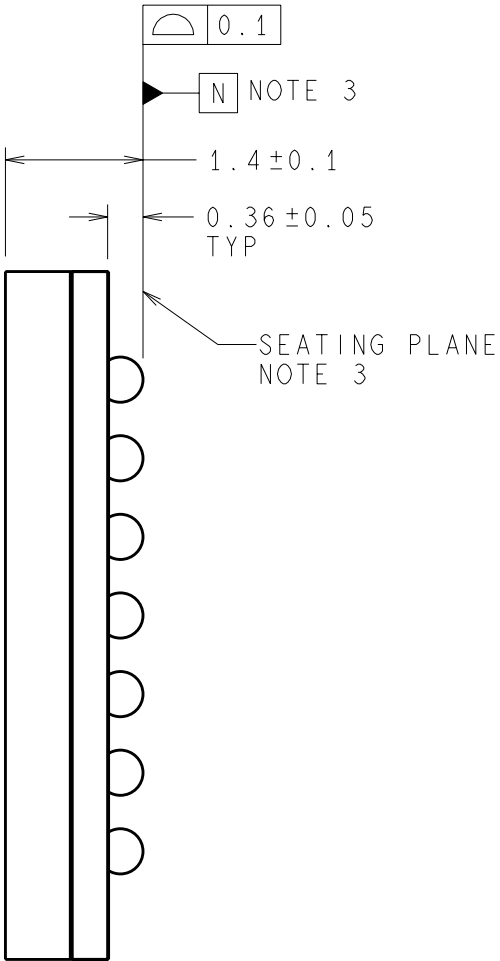
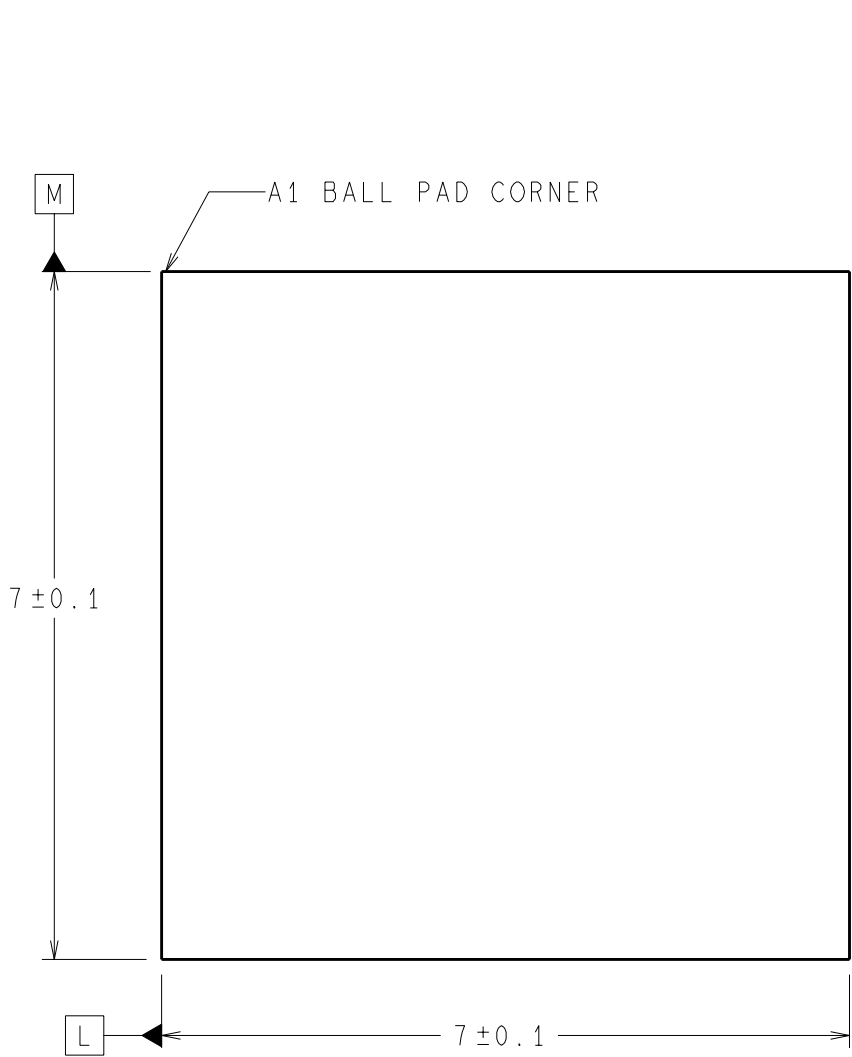


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12253	08/14/2000	TL/GN
B	UPDATE THE PKG CORNERS; CHG DWG FORMAT TO B SIZE	907	01/07/2003	TL/AT



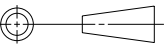
49X $\varnothing 0.46 \pm 0.05$				
$\varnothing$	$\varnothing 0.15 \text{ (M)}$	N	L (S)	M (S)
	$\varnothing 0.08 \text{ (M)}$	N		

NOTE 2

NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
- DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
- PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- NO JEDEC REGISTRATION AS OF JANUARY 2003.

DIMENSIONS ARE IN MILLIMETERS

APPROVALS		DATE		 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	T. LEQUANG		08/14/2000		
DFTG. CHK.	MARTA SUCHY	01/07/2003		FBGA, PLASTIC, LAMINATED, 7 X 7 X 1.4 mm BODY, 49 BALL, 0.8 mm PITCH	
ENGR. CHK.	ANNY TU	01/07/2003			
PROJECTION  MM		SCALE	SIZE	DRAWING NUMBER	REV
		NTS	B	(SC)MKT-SLC49A	B
FORMERLY: N/A				SHEET 1 of 1	